

What is claimed is:

1. A function module comprising:
2 a first circuit board including a first surface,
3 with a first ground layer formed thereon;
4 a second circuit board, coupled to the first circuit
5 board, including a second surface facing the
6 first surface, wherein a second ground layer is
7 formed on the second surface; and
8 a plate-type heat dissipation device, disposed
9 between the first circuit board and the second
10 circuit board, abutting the first ground layer
11 and the second ground layer respectively.

1. The function module as claimed in claim 1,
2 wherein the first circuit board further includes a third
3 surface, opposite to the first surface, with a first
4 device located thereon.

1. The function module as claimed in claim 1,
2 wherein the second circuit board further includes a
3 fourth surface, opposite to the second surface, with a
4 second device located thereon.

1. The function module as claimed in claim 1,
2 wherein the first ground layer comprises a copper layer.

1. The function module as claimed in claim 1,
2 wherein the second ground layer comprises a copper layer.

1. The function module as claimed in claim 1,
2 further comprising a flat cable connecting the first

3 circuit board and the second circuit board, providing
4 communicability therebetween.

1 7. The function module as claimed in claim 1,
2 wherein the first circuit board includes a first
3 connector, the second circuit board includes a second
4 connector corresponding to the first connector, and the
5 first circuit board and the second circuit board
6 communicate with each other by the respective connectors.

1 8. The function module as claimed in claim 7,
2 wherein the first connector is located on the first
3 surface, and the second connector is located on the
4 second surface.

1 9. The function module as claimed in claim 1,
2 further comprising a slot connector connecting the first
3 circuit board and the second circuit board, providing
4 communicability therebetween.

1 10. The function module as claimed in claim 1,
2 wherein the plate-type heat dissipation device is a
3 plate-type heat pipe, a copper plate, a plate-type copper
4 block, a micro fin, a water-cooling device, or a vapor
5 chamber.

1 11. The function module as claimed in claim 1,
2 further comprising a heat dissipation fin, connected to
3 the plate-type heat dissipation device, for further
4 dissipation of heat therefrom.

1 12. The function module as claimed in claim 11,
2 further comprising a fan, connected to the heat

3 dissipation fin, for further dissipation of heat
4 therefrom.

1 13. The function module as claimed in claim 1,
2 further comprising:

3 a first adhesion layer, disposed between the plate-
4 type heat dissipation device and the first
5 ground layer, for combining the plate-type heat
6 dissipation device with the first circuit
7 board; and

8 a second adhesion layer, disposed between the plate-
9 type heat dissipation device and the second
10 ground layer, for combining the plate-type heat
11 dissipation device with the second circuit
12 board.

1 14. The function module as claimed in claim 13,
2 wherein both the first adhesion layer and the second
3 adhesion layer comprise one selected from the group
4 consisting of brazing solder, tin solder, thermal
5 interface material, grease and the combination thereof
6 respectively.

1 15. A function module comprising:

2 a first circuit board including a first surface with
3 a first heat conduction layer formed thereon;
4 a second circuit board, coupled to the first circuit
5 board, including a second surface facing the
6 first surface, on which a second heat
7 conduction layer is formed; and

8 a plate-type heat dissipation device, disposed
9 between the first circuit board and the second
10 circuit board, abutting the first heat
11 conduction layer and the second heat conduction
12 layer respectively.

1 16. The function module as claimed in claim 15,
2 wherein the first heat conduction layer is a ground layer
3 of the first circuit board, and the second heat
4 conduction layer is a ground layer of the second circuit
5 board.

1 17. The function module as claimed in claim 15,
2 wherein the first circuit board further includes a third
3 surface, opposite to the first surface, with a first
4 device located thereon.

1 18. The function module as claimed in claim 15,
2 wherein the second circuit board further includes a
3 fourth surface, opposite to the second surface, with a
4 second device located thereon.

1 19. The function module as claimed in claim 15,
2 wherein the first heat conduction layer comprises a
3 copper layer.

1 20. The function module as claimed in claim 15,
2 wherein the second heat conduction layer comprises a
3 copper layer.

1 21. The function module as claimed in claim 15,
2 further comprising a flat cable connecting the first

3 circuit board and the second circuit board, providing
4 communicability therebetween.

1 22. The function module as claimed in claim 15,
2 wherein the first circuit board includes a first
3 connector, the second circuit board includes a second
4 connector corresponding to the first connector, and the
5 first circuit board and the second circuit board
6 communicate with each other by the respective connectors.

1 23. The function module as claimed in claim 22,
2 wherein the first connector is located on the first
3 surface, and the second connector is located on the
4 second surface.

1 24. The function module as claimed in claim 15,
2 further comprising a slot connector connecting the first
3 circuit board and the second circuit board, providing
4 communicability therebetween.

1 25. The function module as claimed in claim 15,
2 wherein the plate-type heat dissipation device is a
3 plate-type heat pipe, a copper plate, a plate-type copper
4 block, a micro fin, a water-cooling device, or a vapor
5 chamber.

1 26. The function module as claimed in claim 15,
2 further comprising a heat dissipation fin, connected to
3 the plate-type heat dissipation device, for dissipating
4 heat therefrom.

1 27. The function module as claimed in claim 26,
2 further comprising a fan, connected to the heat
3 dissipation fin, for dissipating heat therefrom.

1 28. The function module as claimed in claim 15,
2 further comprising:

3 a first adhesion layer, disposed between the plate-
4 type heat dissipation device and the first heat
5 conduction layer, attaching the plate-type heat
6 dissipation device to the first circuit board;
7 and

8 a second adhesion layer, disposed between the plate-
9 type heat dissipation device and the second
10 heat conduction layer, attaching the plate-type
11 heat dissipation device to the second circuit
12 board.

1 29. The function module as claimed in claim 28,
2 wherein both the first adhesion layer and the second
3 adhesion layer comprise one selected from the group
4 consisting of brazing solder, tin solder, thermal
5 interface material, or grease and the combination thereof
6 respectively.